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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Kiyoshi Arita	08/16/2005
Hiroshi Haji	08/16/2005
Kazuhiro Noda	08/16/2005
Akira Nakagawa	08/16/2005
Teruaki Nishinaka	08/16/2005

RECEIVING PARTY DATA

Name:	Matsushita Electric Industrial Co., Ltd.	
Street Address:	1006, Oaza Kadoma, Kadoma-shi,	
City:	Osaka	
State/Country:	JAPAN	
Postal Code:	571-8501	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11183739

CORRESPONDENCE DATA

Fax Number: (202)912-0774

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 2029123800

Email: PPC@us.panasonic.com

Correspondent Name: Kenji Kamata

Address Line 1: 1130 Connecticut Ave., N.W., Suite1100

Address Line 2: Panasonic Patent Center

Address Line 4: Washington, DISTRICT OF COLUMBIA 20036

NAME OF SUBMITTER: Chika Eda

Total Attachments: 2

500058671

PATENT REEL: 016729 FRAME: 0802 40.00 11183

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PATENT REEL: 016729 FRAME: 0803

ASSIGNMENT

Matsushita Ref. P039104-02	Application Serial No. <u>11/183,739</u>	
Japanese Firm Ref: 542429	5_1149A	
WHEREAS, the undersigned has (have) invented the invention entitled	<u>:</u>	
Box 1		
Title of Invention:	SES ADDAMOENENT DET	EDMINIATION METHOD AND
MANUFACTURING METHOD FOR SEMICONDUCTOR DEVI	•	
APPARATUS FOR SEMICONDUCTOR DEVICE FORMATION	·	I FOR DETERMINING
ARRANGEMENT OF SEMICONDUCTOR DEVICE FORMATION		
1. For use when signing Declaration prior to filin	g U.S. patent application (check only	one box below)
(a)□ for which an application for U.S. patent has been execute	ed by the undersigned concur	rently herewith, or
(b) for which an application for U.S. patent has been execute date(s):, or (if the Declaration and Assignment are signed on the same day, check (a) and make no entry in the.	Q	Assignment, enter the date(s) on which you signed the
Declaration)		
(c) for which an International Application has been filed as: (for the PCT-US national entry, check only (c) and enter PCT application number in the right)	PCT Application No.	and,
2. For use when signing Declara	tion after filing U.S. patent application	
(d) $\mathbf{\overline{y}}$ for which an application for U.S. patent has been filed	Application Filing	July 19, 2005 and,
on:	Date	, ·-, <u>-</u>

WHEREAS, Matsushita Electric Industrial Co., Ltd. of 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501, JAPAN, its heirs, successors, legal representatives and assigns (hereinafter designated as "Assignee") is desirous of acquiring the entire right, title, and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged and intended to be legally bound hereby, the undersigned, by these presents, does sell, assign and transfer unto said Assignee the entire and exclusive right, title and interest in and to; (i) said invention in the United States of America, its territories, dependencies and possessions (hereinafter designated as the United States) and in all countries foreign to the United States; and (ii) this patent application and any and all related patent application(s) disclosing said invention, including provisionals, non-provisionals, conversions, continuations, continuations-in-part and reissues thereof in the United States and all countries foreign to the United States (hereinafter designated as "Related Applications"), along with all rights of priority created by this patent application under any treaty relating thereto; and (iii) any and all Letters Patent(s), including all renewals, extensions, reissues and reexamination certificates which may be granted therefore, and all rights to sue for past and future infringement thereunder, in the United States and in all countries foreign to the United States for the full term or terms thereof.

The undersigned agree(s) to execute all papers necessary in connection with this application and any and all Related Applications thereof, all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements, all papers necessary in connection with any interference which may be declared concerning this application or any and all Related Applications thereof and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference, and for any and all litigations regarding, or for the purpose of protecting the right, title and interest in and to said invention, this application and any and all Related Applications or Letters Patent(s) therefore, and to testify in any legal proceeding relating thereto and in support thereof, for the benefit of Assignee, and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States and any foreign patent(s) to the Assignee and to vest all rights hereby conveyed to the Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents, and officials of all foreign countries, whose duty is to issue patents, to issue any and all Letters Patent(s) resulting from said application or any and all Related Applications thereof to said Assignee and hereby covenants that the undersigned has (have) full right to convey the entire interest herein assigned, and that the undersigned has (have) not executed, and will not execute, any assignment, sale, agreement or encumbrances in conflict herewith.

The undersigned hereby does sell, assign and transfer unto said Assignee the full and exclusive authority for revoking power of attorney(s) executed by the undersigned in connection with this application and for appointing a new power of attorney in place thereof.

The undersigned hereby grant(s) the Assignee and the appointed U.S. patent attorneys and agents the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent Office for recordation of this document.

The undersigned hereby agree(s) that the above obligations shall apply to the undersigned both individually and collectively.

The undersigned hereby agree(s) that this Assignment shall be construed in accordance with the law of the appropriate jurisdiction within the United States.

IN WITNESS WHEREOF, executed by the undersigned on the date(s) following the undersigned name(s) and signature(s).

Box2 (Each Inventor, please Sign and Date below)			
	(e) First Name, Last Name	(f) Signature	(g) Date signed
(1)	Kiyoshi ARITA	Kiyoki Arita	August 16, 2005
(2)	Hiroshi HAJI	Hirosli Heji	AUG. 16, 2005
(3)	Kazuhiro NODA	Kazukiro noda	AUG. 16, 2005
(4)	Akira NAKAGAWA	Akira nakagawa	AUG. 16, 2005

☑Check if additional paper(s) is/are attached. Total of 2 pages are submitted.

REEL: 016729 FRAME: 0804

ASSIGNMENT (Cont., Page 2 of 2)

Matsushita Ref. P039104-02	Application Serial No. 11/183,739	
Japanese Firm Ref: 542429	US Firm Ref: 2005_1149A	

Additional Inventors:

Box2 (Continued)			
	(e) First Name, Last Name	(f) Signature	(g) Date signed
(5)	Teruaki NISHINAKA	Ternaki Nishinaka	Aug. 16, 2005
(6)			
(7)			
(8)			
(9)			
(10)			
(11)			
(12)			
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□Check if additional paper(s) is/are attached. Total of ____ pages are submitted.

PATENT REEL: 016729 FRAME: 0805